

REFERENCE

SPEC. No. ED-05G200E

ISSUE April 26, 2012

SHARP

SYSTEM DEVICE DIVISION
ELECTRONIC COMPONENTS AND DEVICES GROUP
SHARP CORPORATION

SPECIFICATION

DEVICE SPECIFICATION FOR

PHOTOINTERRUPTER

MODEL No.

GP1S196HCPSF

Enclosed please find copies of the Specifications which consists of 18 pages including cover.
This specification sheets and attached sheets shall be both side copy.
After confirmation of the contents, please be sure to send back ☐ 1 copy of the Specifications
with approving signature on each.

CUSTOMER'S APPROVAL

DATE

BY

PRESENTED

DATE

Apr. 27, 2012

BY

T. Ichinose

T. Ichinose,
Department General Manager of
Development Dept. III
System Device Division
Electronic Components and Devices Group
SHARP CORPORATION

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Product name : PHOTOINTERRUPTER

Model No. : GP1S196HCPSF

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2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below.

Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.

- (2) This product is designed for use in the following application areas ;

• OA equipment	• Audio visual equipment	• Home appliances
• Telecommunication equipment (Terminal)	• Measuring equipment	
• Tooling machines	• Computers	

If the use of the product in the above application areas is for equipment listed in paragraphs

- (3) or (4), please be sure to observe the precautions given in those respective paragraphs.

- (3) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as ;

• Transportation control and safety equipment (aircraft, train, automobile etc.)
• Traffic signals • Gas leakage sensor breakers • Rescue and security equipment
• Other safety equipment

- (4) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as ;

• Space equipment	• Telecommunication equipment (for trunk lines)
• Nuclear power control equipment	• Medical equipment
• Power generation and power transmission control system (Key system)	

- (5) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above four paragraphs.
3. Please contact and consult with a Sharp sales representative for any questions about this product.

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1. Application

This specification applies to the outline and characteristics of transmissive type photointerrupter; Model No. GP1S196HCPST.

2. Outline : Refer to the attached drawing No. CY12903i02.

3. Ratings and characteristics : Refer to the attached sheet, Page 5, 6, 7.

4. Reliability : Refer to the attached sheet, Page 8.

5. Outgoing inspection : Refer to the attached sheet, Page 9.

6. Supplements

6.1 Parts

Refer to the attached sheet, Page 10.

6.2 Packing

Refer to the attached drawing No. CY12904i09B

6.3 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform)

6.4 Specified brominated flame retardants

Specified brominated flame retardants (PBB and PBDE) are not used in this device at all.

6.5 Compliance with each regulation

6.5.1 The RoHS directive(2002/95/EC)

This product complies with the RoHS directive(2002/95/EC) .

Object substances: mercury, lead, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE)

6.5.2 Content of six substances specified in Management Methods for Control of Pollution Caused by Electronic Information Products Regulation (Chinese : 电子信息产品污染控制管理办法).

Category	Toxic and hazardous substances					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent chromium (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Photointerrupter	✓	✓	✓	✓	✓	✓

✓ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard .

6.6 Product mass : Approx. 20mg

6.7 Taping specification : Refer to the attachment-2.

6.8 Moisture-proof package specification : Refer to the attachment-3.

6.9 Country of origin : Japan and China

7. Notes

7.1 Circuit design

In circuit designing, make allowance for the degradation of the light emitting diode output that results from long continuous operation. (50% degradation/5 years)

7.2 Prevention of detection error

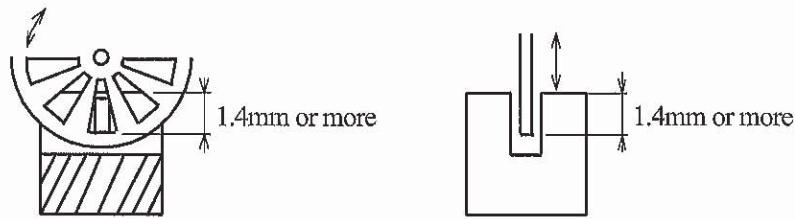
To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

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7.3 Position of opaque board

Opaque board shall be installed at place 1.4mm or more from the top of elements.

(Example)



7.4 Print circuit board design

Because a portion of the internal lead may be exposed at the back of the product, please consider it in the pattern design for a print circuit board design.

7.5 Soldering

(1) Reflow soldering

Please do only one soldering at the temperature and the time within the temperature profile in attachment-1.

(2) Hand soldering

To solder onto lead pins, please iron ahead temperature at 260°C for 3 seconds or less.

Please also take care not to let mechanical stress exert on package and lead pins when soldering.

Please have soldering adjustment, etc. after GP1S196HCPSF is cooled down, and also note that the outer mold resin may be meltdown by heating for a long time.

Since the tip of the lead has exposed lead frame base material, there is a case not to be soldered, so please consider the soldering pattern on a print circuit board to solder well with the bottom and side surface of the lead.

7.6 Cleaning

Cleaning shall be carried out under the below conditions to avoid keeping solvent, solder and flux on the device.

- (1) Solvent cleaning : Solvent temperature 45°C or less, Immersion for 3 min. or less
- (2) Ultrasonic cleaning : Since the influence to the product may changes by the conditions of the ultrasonic power, time, the tank size, PCB size, the product installation condition, etc., please evaluate with actual conditions and confirm before usage.
- (3) The cleaning shall be carried out with solvent below.

Solvent : Ethyl alcohol, Methyl alcohol

7.7 Lead pin

Lead terminals of this product are tin copper alloy plated. Before usage, please evaluate solder ability with actual conditions and confirm. The uniformity in color for the lead terminals are not specified.

7.8 Storage and management after open

7.8.1 Storage condition : Storage shall be in accordance with the below conditions.

Storage temp. : 5 to 30°C

Storage humidity : 70%RH or less

7.8.2 Treatment after open

- (1) After open, please mount at the conditions of humidity 60%RH or less and temperature 5 to 25°C within 2 days.
- (2) In case of long time storage after open, please storage at the conditions of humidity 70%RH or less and temperature 5 to 30°C by using dry box or resealing with desiccant in moisture-proof bag by sealer and mount within 2 weeks.

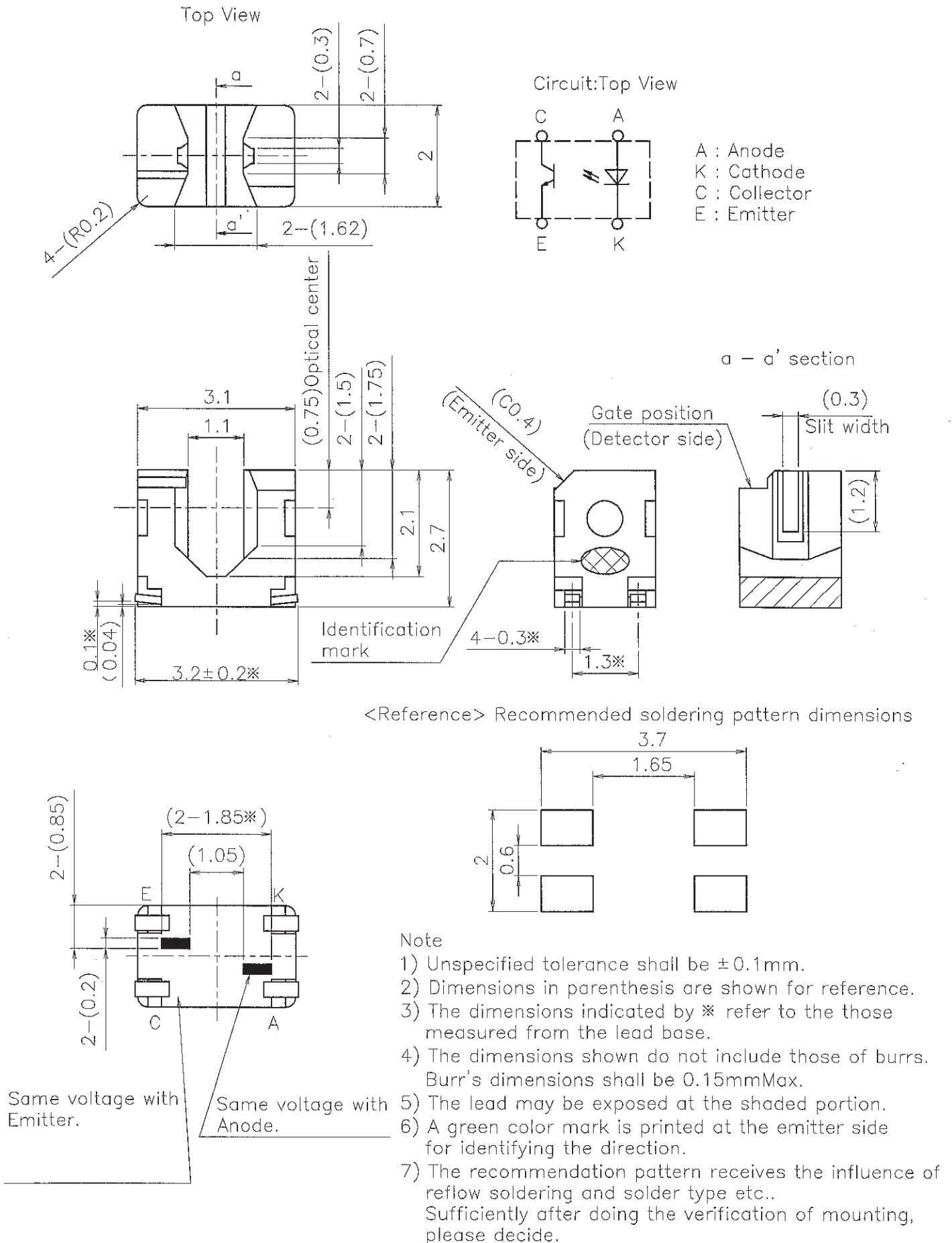
7.8.3 Baking before mounting

In case that it could not carry out the above treatment, it is able to mount with baking treatment.

However baking treatment shall be limited only 1 time. Although it is possible to have baking treatment with taping package, please bake it by putting a reel with standing situation. Please do not lay it down since it may change the reel shape and occur a mounting problem. Since a label and a fixing tape for the carrier tape does not have enough heat resistance, there may be a case to leave some paste.

Recommended baking conditions : 100°C, 16 to 24 hours

2.1 Outline Dimensions (Drawing No.CY12903i02) Scale:10/1 Unit:mm



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3. Ratings and characteristics

3.1 Absolute maximum ratings

Ta=25°C

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	30	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_c	20	mA
	Collector power dissipation	P_c	75	mW
Total power dissipation		P_{tot}	100	mW
Operating temperature		T_{opr}	-25 to +85	°C
Storage temperature		T_{stg}	-40 to +100	°C
* soldering temperature		T_{sol}	260	°C

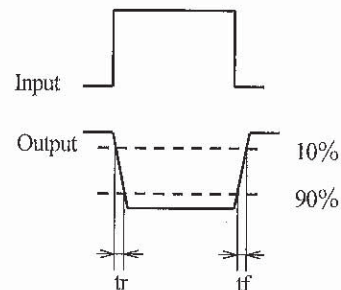
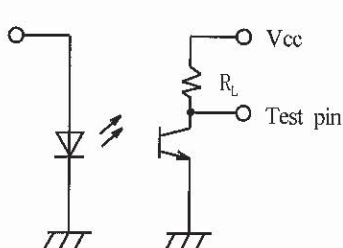
* Soldering time : 3 s or less

3.2 Electro-optical characteristics

Ta=25°C

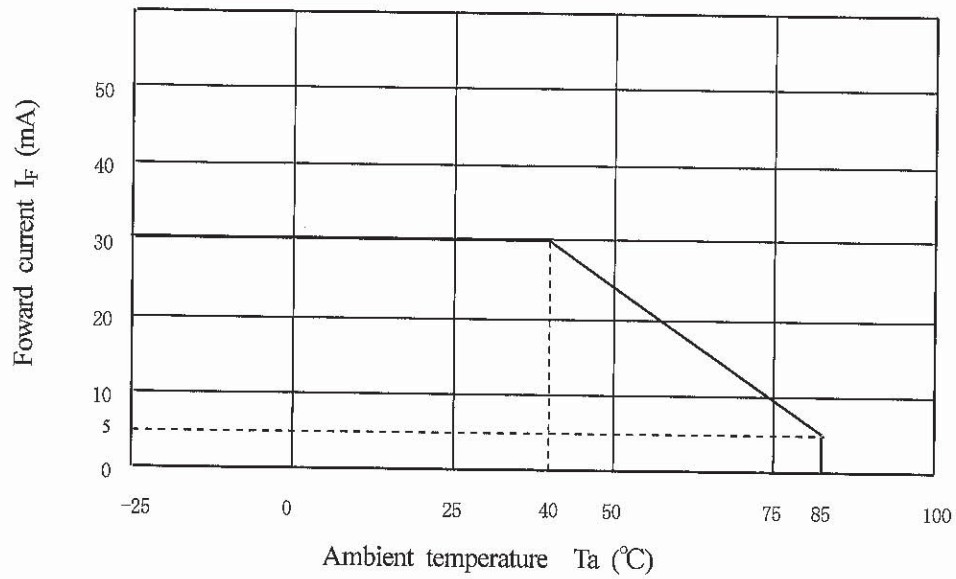
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V_F	$I_F=20\text{mA}$	-	1.2	1.4	V
	Reverse current	I_R	$V_R=3\text{V}$	-	-	10	μA
Output	Collector dark current	I_{CEO}	$V_{CE}=20\text{V}$	-	-	100	nA
Transfer characteristics	Collector current	I_c	$V_{CE}=5\text{V}, I_F=5\text{mA}$	100	-	400	μA
	Response time	(Rise)	$V_{CE}=5\text{V}, I_c=100\mu\text{A}$ $R_L=1\text{k}\Omega$	-	50	150	μs
		(Fall)		-	50	150	μs
	Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_F=10\text{mA}, I_c=40\mu\text{A}$	-	-	0.4	V

(Test circuit for response time)

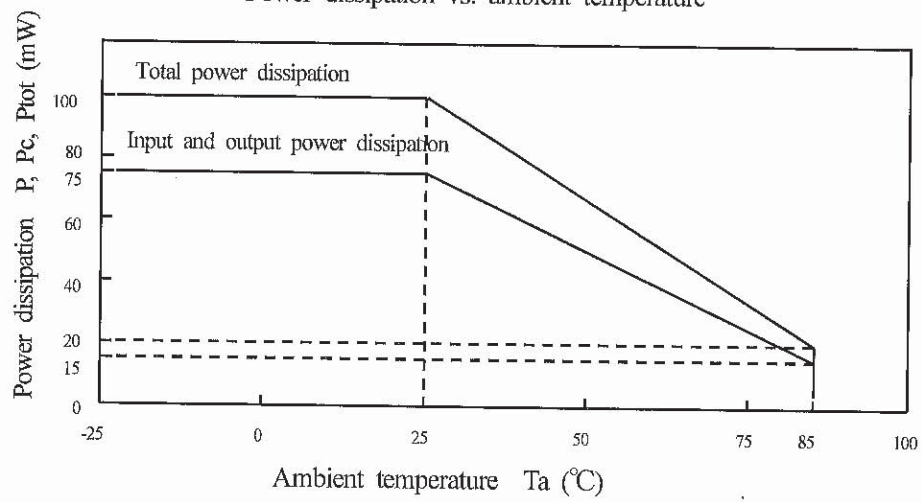


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Forward current vs. ambient temperature

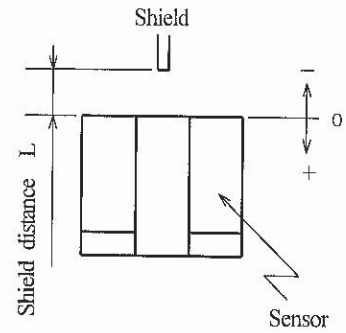
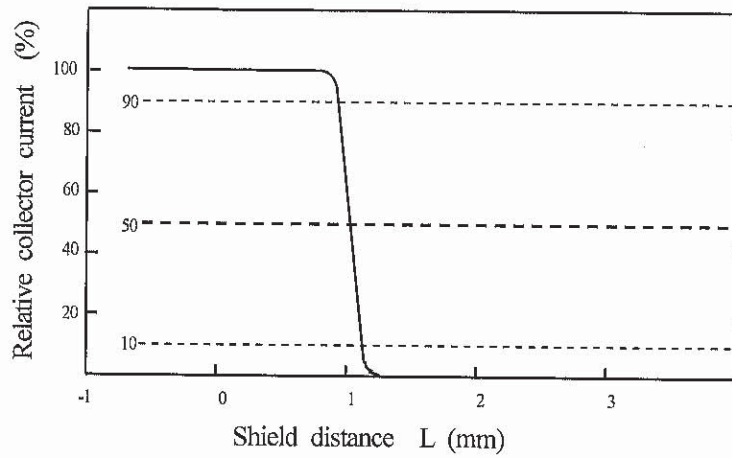


Power dissipation vs. ambient temperature



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Relative collector current vs. shield distance 1 (Reference value)



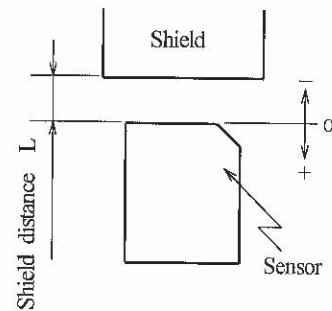
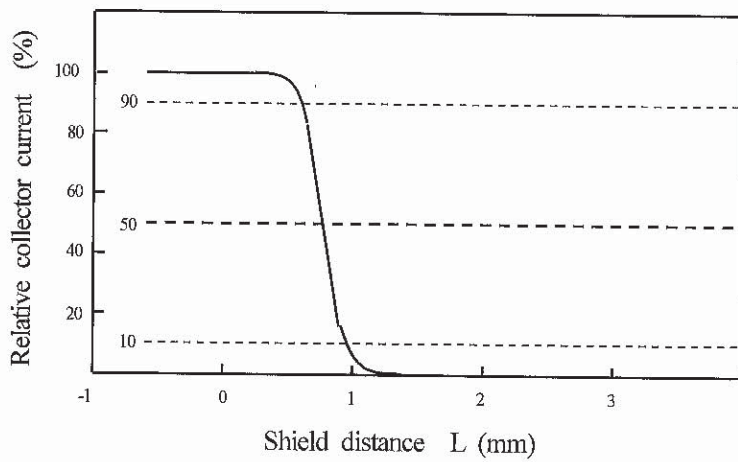
Test condition

$$I_F = 5.0\text{mA}$$

$$V_{CE} = 5\text{V}$$

$$T_a = 25^\circ\text{C}$$

Relative collector current vs. shield distance 2 (Reference value)



Test condition

$$I_F = 5.0\text{mA}$$

$$V_{CE} = 5\text{V}$$

$$T_a = 25^\circ\text{C}$$

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4. Reliability

The reliability of products shall satisfy items listed below.

Confidence level : 90%

LTPD : 10 or 20

Test Items	Test Conditions	Failure Judgment Criteria	Samples (n)
			Defective (c)
Temperature cycling	1 cycle -40°C to +100°C (30min) (30min) 20 cycles test	$I_R \geq U \times 2$ $I_{CBO} \geq U \times 2$ $V_F \geq U \times 1.2$ $I_c \leq L \times 0.8$ U: Upper specification limit L: Lower specification limit	n=22, c=0
humidity storage	+60°C, 90%RH, 500h		n=22, c=0
High temp. storage	+100°C, 500h		n=22, c=0
Low temp. storage	-40°C, 500h		n=22, c=0
Operation life	$I_F=20\text{mA}$, $T_a=25^\circ\text{C}$, 500h		n=22, c=0
Mechanical shock	15000m/s ² , 0.5ms 3 times/ $\pm X$, $\pm Y$, $\pm Z$ direction		n=11, c=0
Variable frequency vibration	100 to 2000 to 100Hz/20min 2h/X, Y, Z direction 100m/s ²		n=11, c=0
Reflow soldering *	Reflow soldering condition : Attachment-1 Time of reflow soldering : 1 time	$I_c < L \times 0.8$	n=11, c=0

* : The alloy composition of solder used for lead free should be Sn-2.5Ag-1Bi-0.5Cu or Sn-3.0Ag-0.5Cu.
Flux used for precleaning should be equivalent to EC-19S-8(TAMURA KAKEN CORPORATION).

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5. Outgoing inspection

5.1 Inspection items

(1) Electrical characteristics

V_F , I_R , BV_{ECO} , BV_{CEO} , I_C , I_{CEO} , $V_{CE(sat)}$

(2) Appearance

5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied.

The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL (%)
Major defect	Characteristics defect	0.065
Minor defect	Defects on appearance *	0.25

※ { Crack ... Visible crack shall be defect.
Split
Chip ... One which affects the electrical characteristics shall be defect.
Scratch
The others }

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6. Supplements

6.1 Parts

This product uses the below parts.

6.1.1 Light detector (Quantity : 1)

Type	Material	Maximum sensitivity (nm)	Sensitivity (nm)	Response time (μ s)
Phototransistor	Silicon (Si)	930	700 to 1200	20

6.1.2 Light emitter (Quantity : 1)

Type	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared light emitting diode (non-coherent)	GaAs	950	0.3

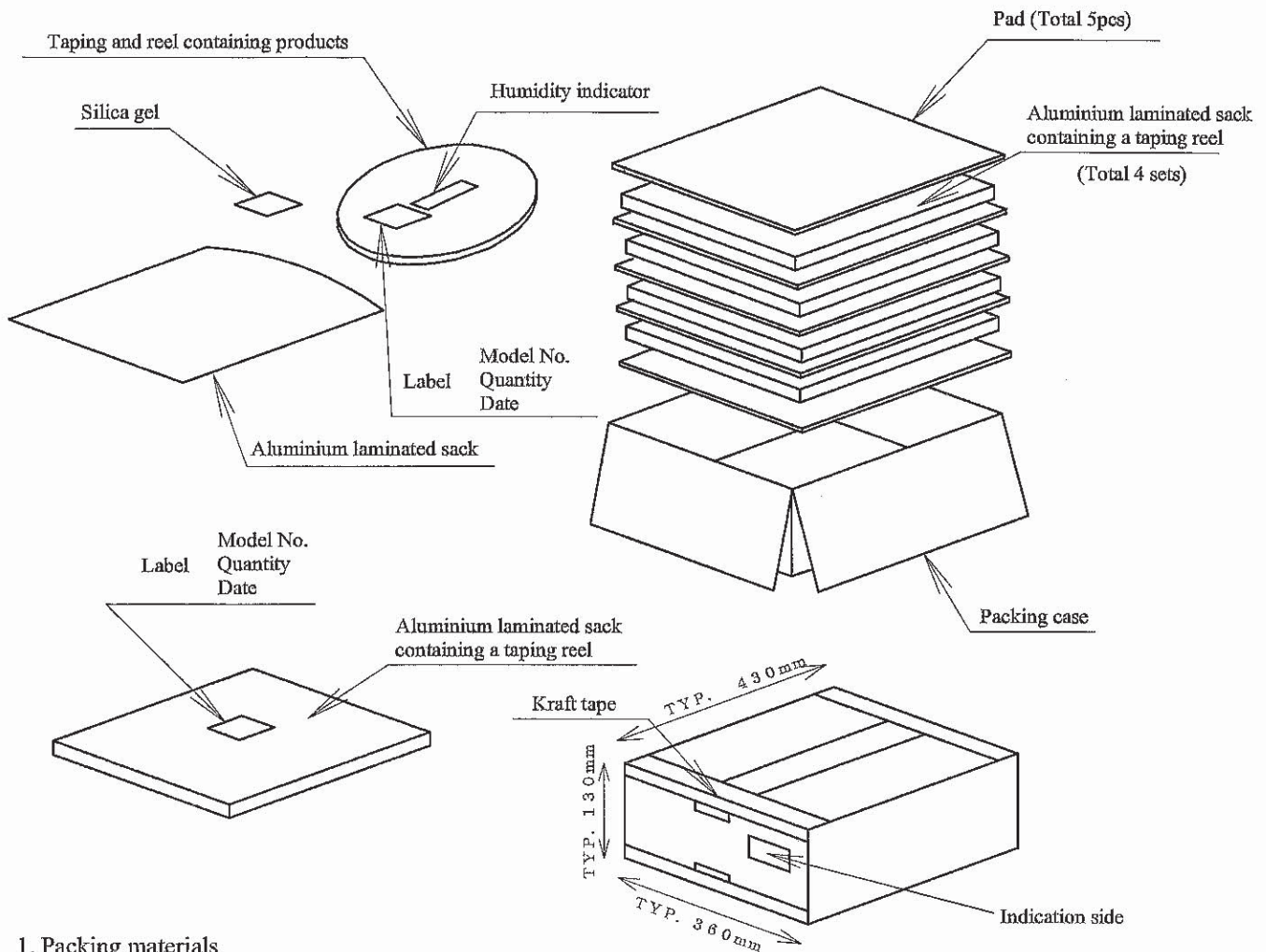
6.1.3 Material

Case	Lead frame	Lead frame plating
Black PPS resin (UL 94V-0)	42 Alloy	SnCu plating

6.1.4 Others

This product shall not be proof against radiation flux.

6.5 Packing (Drawing No. CY12904i09B)



1. Packing materials

No.	Name	Material	The number of use
1	Packing case	Paper corrugated	1
2	Pad	Cardboard	5
3	Reel	PPE	4
4	Carrier tape	PC	4
5	Cover tape	PET	4
6	Label	Paper	8
7	Silica gel	-	4
8	Humidity indicator	Paper	4
9	Aluminium laminated sack	Al-Polyethylene	4
10	Kraft tape	-	-

2. Packing Quantity

- 1. Packing reel : 5000pcs / One reel
- 2. Packing case : 20000pcs / One case
(Gross weight : Approx. 3.2kg)

3. Indication items

The contents of the carton indication conforms to EIAJ C-3 and the following items are indicated.
Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin

4. Packing method

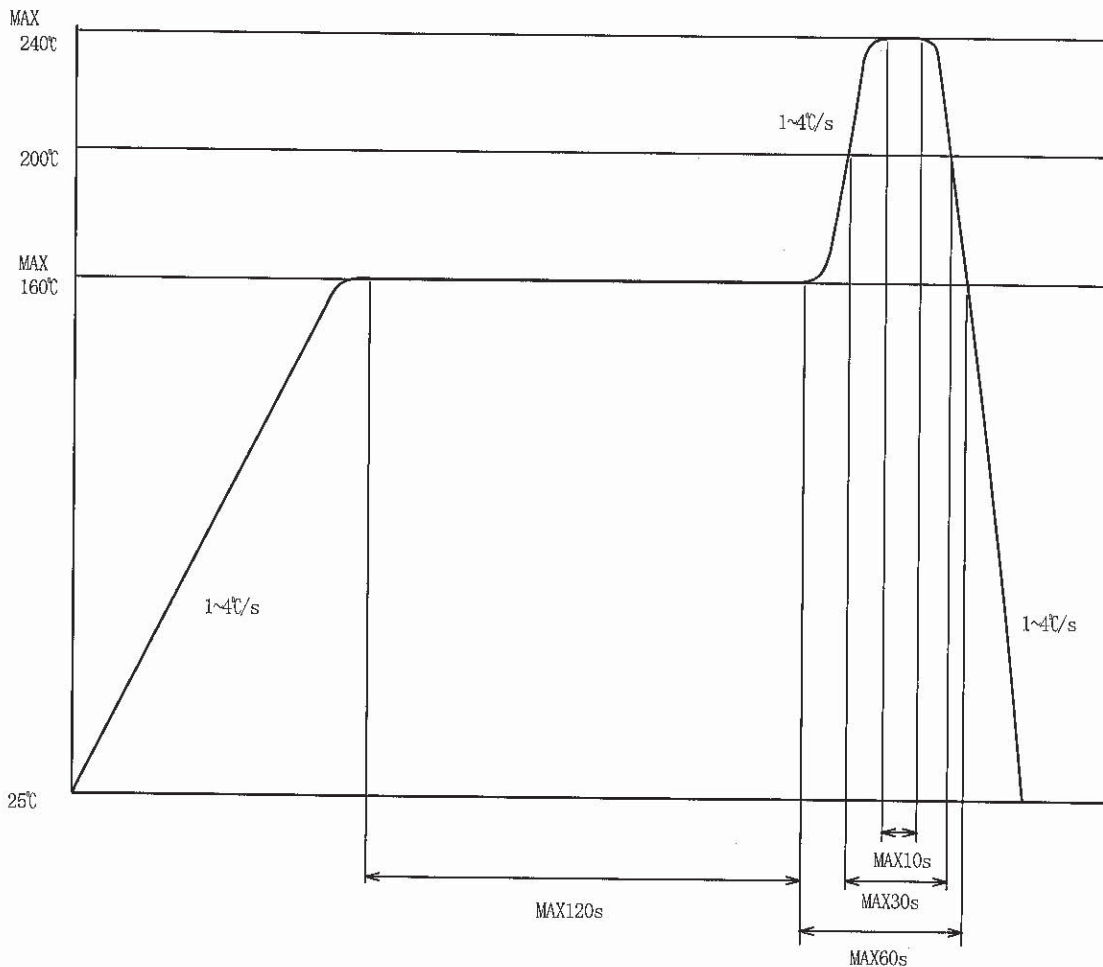
- A taping reel containing 5,000pcs products with a label and an indicator are put into an Aluminium laminated sack with a silica gel and seal the sack.
- Put a label which has Model No., quantity and date on the sack.
- 4 sacks are contained to a packing case with pads which are put upper and bottom of each sack.
- The packing case is sealed off with the kraft tape.
Indicates Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin on the packing case.

(Attachment-1)

Precautions for Soldering photointerrupter

1. In case of reflow soldering,

Please do only one soldering at the temperature and the time within the temperature profile as shown in the figure below.



2. Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin.

So keep the package temperature within that specified in Item 1.

Also avoid immersing the resin part in the solder.

Even if within the temperature profile above, there is the possibility that the

gold wire in package is broken in case that the deformation of PCB gives the affection to lead pins.

Please use after confirmation the conditions fully by actual solder reflow machine.

(Attachment-2-1)

Package specifications (φ330mm reel)

1. Application

This specification applies to the taping specifications and the relation items for the GP1S196HCPSF.

2. Taping method

2.1 Tape structure and Dimensions (Refer to the attached sheets-2-2)

2.1.1 The tape shall have a structure in which a cover tape is sealed heat-pressed on the carrier tape made by polystyrene to protect against static electricity.

2.2 Reel structure and Dimensions (Refer to the attached sheets-2-3)

2.3 Direction of product insertion (Refer to the attached sheets-2-3)

2.3.1 Product direction in carrier tape shall direct to the detector at the hole side on the tape.

3. Repair method of sealing error

3.1 In case of repairing a sealing error, three sides of a cover tape matching to the product insertion portion are opened by a cutter and it will be closed by adhesiveness tape after repairing.

4. Adhesiveness of cover tape

4.1 The exhalation force between carrier tape and cover tape shall be 0.2N to 1.0N for the angle from 160° to 180°.

5. Rolling method and quantity

5.1 Wind the tape back on the reel so that the cover tape will be outside the tape.

5.2 Attach more than 25cm of blank tape to the trailer and the leader of the tape and fix the both ends with adhesive tape.

5.3 One reel shall contain 5,000 pcs.

6. Indication items

The contents of the carton indication conforms to EIAJ C-3 and the following items are indicated.

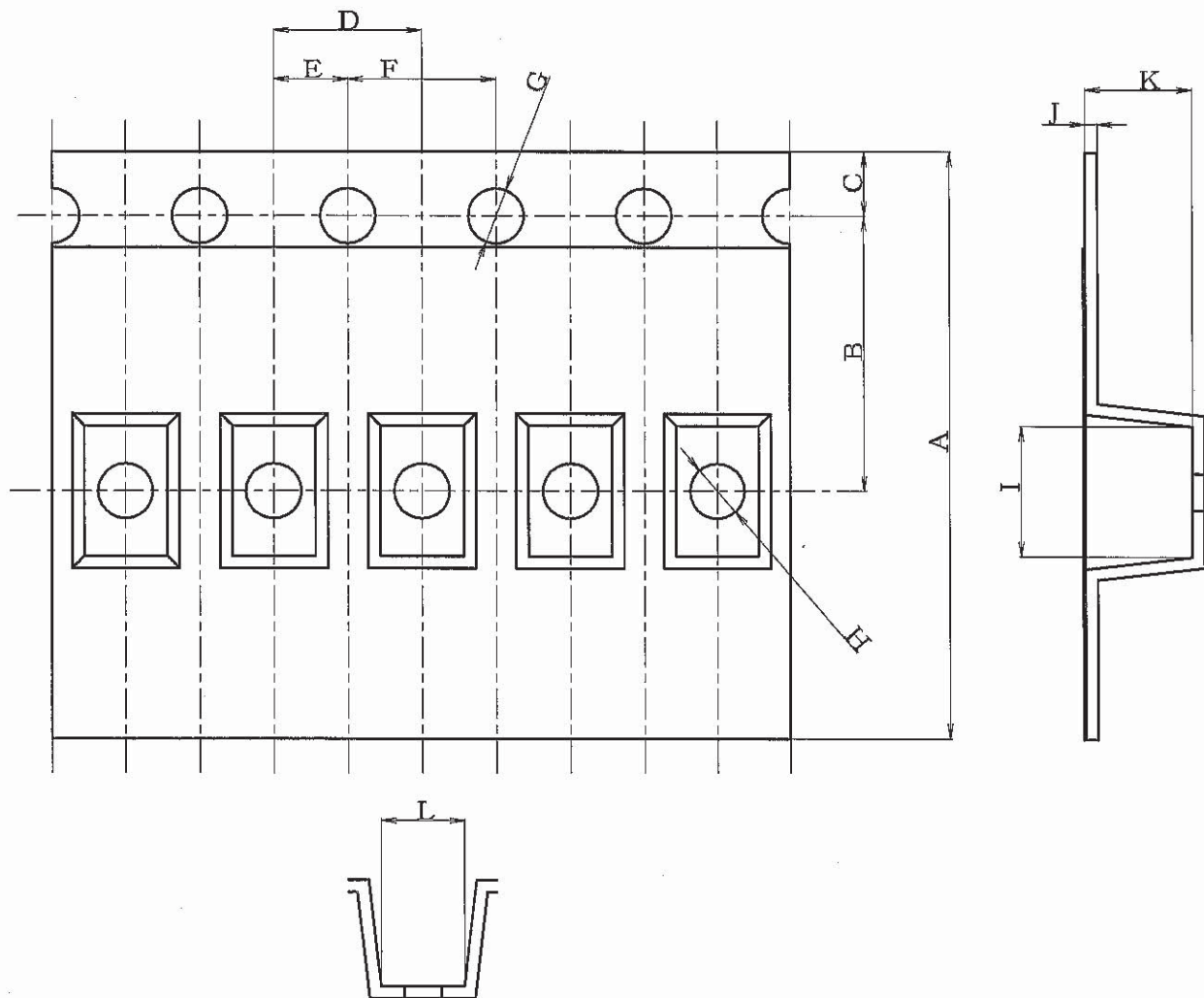
Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin

7. Safety protection during shipping

There shall be no deformation of component or degradation of electrical characteristics due to shipping.

(Attachment-2-2)

2.1 Tape structure and dimensions



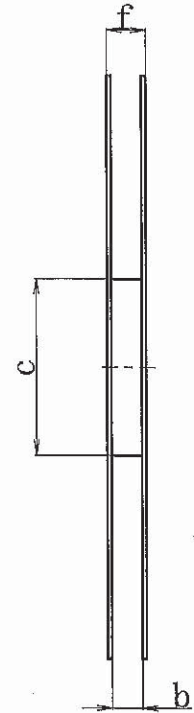
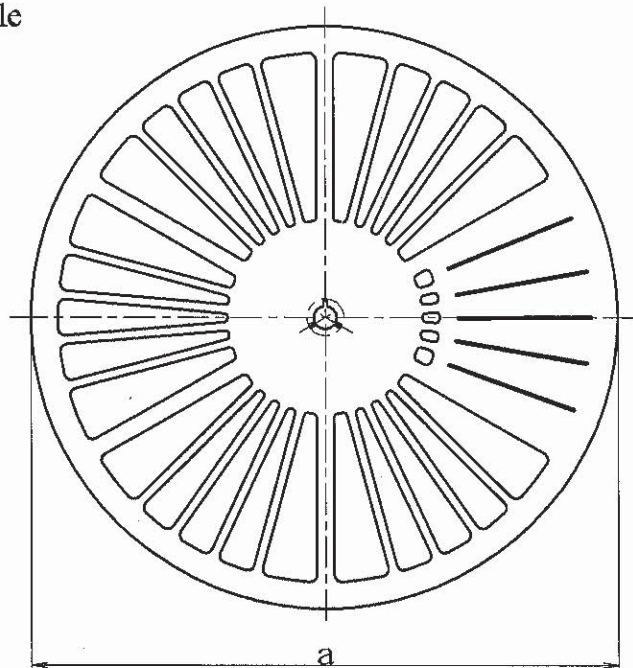
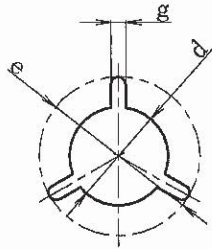
Symbol Unit	Dimensions					
	A	B	C	D	E	F
mm	16.0 ± 0.3	7.5 ± 0.1	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.1	4.0 ± 0.1

Symbol Unit	Dimensions					
	G	H	I	J	K	L
mm	$\phi 1.5 \begin{smallmatrix} +0.1 \\ -0 \end{smallmatrix}$	$\phi 1.5 \pm 0.3$	3.55 ± 0.1	0.33 ± 0.05	2.9 ± 0.1	2.25 ± 0.1

(Attachment-2-3)

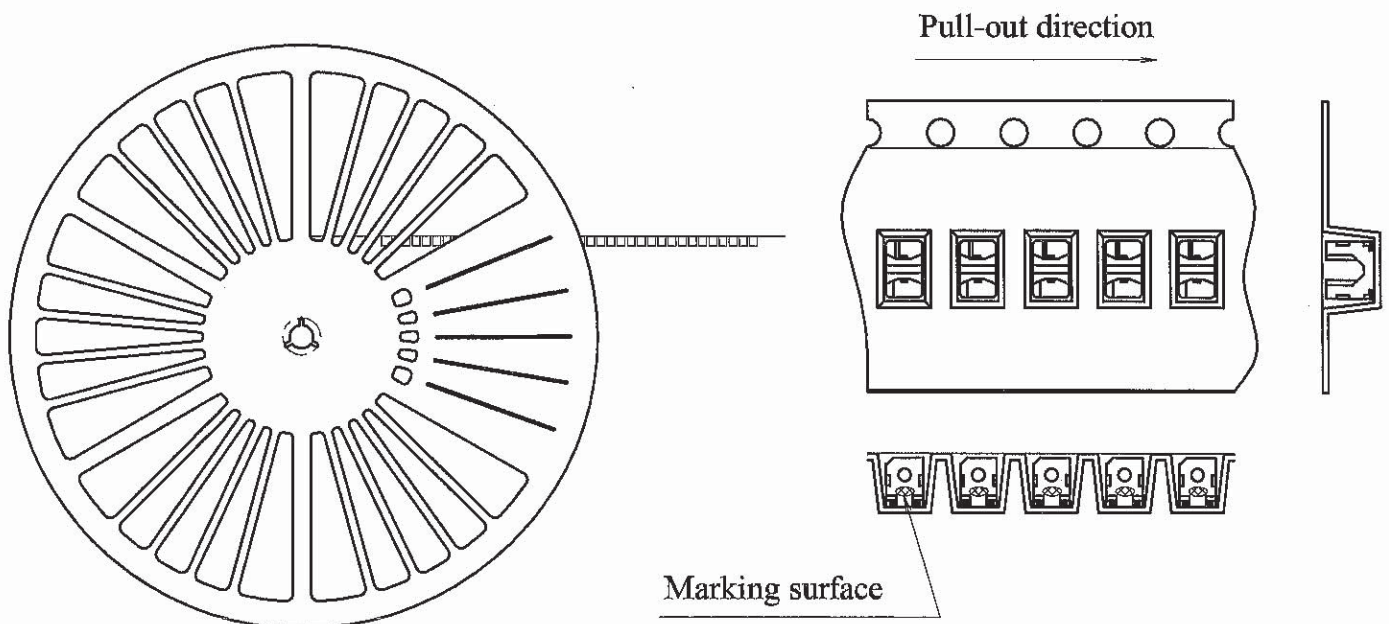
2.2 Reel structure and dimensions

Details for reel fixing hole



Symbol Unit	Dimensions						
	a	b	c	d	e	f	g
mm	330 ± 2.0	17.5 ± 1.0	$\phi 100 \pm 1.0$	13 ± 0.2	21 ± 0.8	22.4 ± 1.0	2 ± 0.5

2.3 Direction of product insertion



(Attachment-3-1)

Moisture-proof package specification

1. Application

This specification applies to the moisture-proof package for the GP1S196HCPSF.

2. Packaging specifications

2.1 Packaging material

Name	Material
Aluminum laminated sack	Aluminum polyethylene
Label	Paper(-made)
Silica gel	-
Outer case	Paper(-made)
Pad	Paper(-made)
Indicator	Paper(-made)

2.2 Packaging method

2.2.1 Seal a reel with 5,000pcs products into an aluminum laminated bag included the ruled silica gel quantity.

2.2.2 Fill up the blank of label and paste on the bag.

2.2.3 Put the moisture-proof laminated bag in the ruled case (4bag/case).

A pad is attached at both top and bottom of every bag.

Package shape	Product	Quantity	Moisture-proof sack Quantity
Tape-reel (φ 330mm)	Single	5,000pcs./reel	1reel/bag

Minimum order Quantity : 5,000pcs (1 reel/bag)

2.2.4 The packing case is sealed off with the kraft tape.

Indicates Model No., Internal production control name, Quantity, Packing date, Corporate name,
Country of origin on the packing case. (20,000 pcs of product in a packing case)

* However 5,000pcs per one reel will be decreased when failure device is removed.

3. Storage and management after open

3.1 Storage condition : Storage shall be in accordance with the below conditions.

Storage temp. : 5 to 30°C

Storage humidity : 70%RH or less

3.2 Treatment after open

(1) After open, please mount at the conditions of humidity 60%RH or less and temperature 5 to 25°C within 2 days.

(2) In case of long time storage after open, please storage at the conditions of humidity 70%RH or less and temperature 5 to 30°C by using dry box or resealing with desiccant in moisture-proof bag by sealer and mount within 2 weeks.

3.3 Baking before mounting

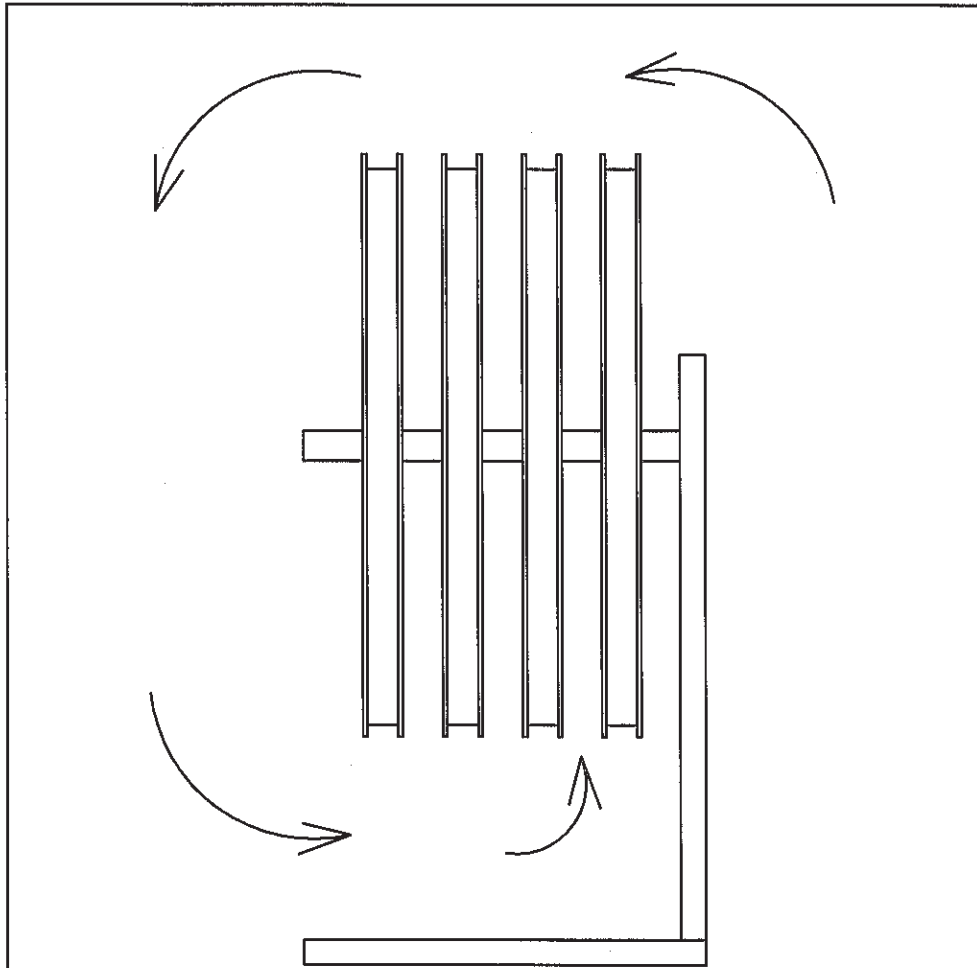
In case that it could not carry out the above treatment, it is able to mount with baking treatment. However baking treatment shall be limited only 1 time. Although it is possible to have baking treatment with taping package, please bake it by putting a reel with standing situation. Please do not lay it down since it may change the reel shape and occur a mounting problem. Since a label and a fixing tape for the carrier tape does not have enough heat resistance, there may be a case to leave some paste.

Recommended baking conditions : 100°C, 16 to 24 hours

(Attachment-3-2)

3.3 Baking treatment before mounting

3.3.1 Placement of reels in an oven



- 1) Please hang reels by using a center hole for fixing the reel.
Please keep some space between reels for better air rotation in the oven.
Please do not lay a reel down in the oven to avoid any damages for the tape edge and the flange of reel.
- 2) Please make sure the carrier tape does not have any slack in a reel before baking to avoid peeling the cover tale off.
Since the tape using for fixing carrier tape is not heatproof, there is a case to remain glue.
So if necessary, please change the tape to a heatproof one.

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